ESD Protection Diode
Low Capacitance Array for High Speed Data Lines

ESD8704

The ESD8704 is designed to protect high speed data lines from ESD. Ultra−low capacitance and low ESD clamping voltage make this device an ideal solution for protecting voltage sensitive high speed data lines. The flow−through style package allows for easy PCB layout and matched trace lengths necessary to maintain consistent impedance between high speed differential lines such as USB 3.0/3.1.

Features

- Low Capacitance (0.5 pF Max, I/O to GND)
- Protection for the Following IEC Standards:
  IEC 61000−4−2 (Level 4)
- Low ESD Clamping Voltage
- SZESD8704MTWTAG − Wettable Flank Package for optimal Automated Optical Inspection (AOI)
- SZ Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC−Q101 Qualified and PPAP Capable
- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant

Typical Applications

- USB 3.0/3.1
- eSATA
- DisplayPort

MAXIMUM RATINGS (T_J = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Operating Junction Temperature Range	T_J	−55 to +125	°C
Storage Temperature Range	T_{stg}	−55 to +150	°C
Lead Solder Temperature − Maximum (10 Seconds)	T_L	260	°C
IEC 61000−4−2 Contact (ESD) IEC 61000−4−2 Air (ESD)	ESD ESD	±30 ±30	kV kV

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

See Application Note AND8308/D for further description of survivability specs.

This document contains information on some products that are still under development. ON Semiconductor reserves the right to change or discontinue these products without notice.

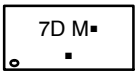
ON Semiconductor®

www.onsemi.com

MARKING DIAGRAM



UDFN10
CASE 517BB



7D = Specific Device Code
M = Date Code
▪ = Pb−Free Package
(Note: Microdot may be in either location)

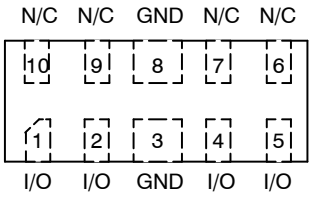


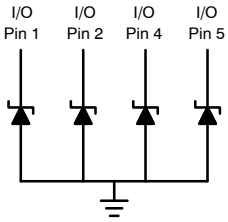
WDFNW10
CASE 515AH



AAA = Specific Device Code
M = Date Code

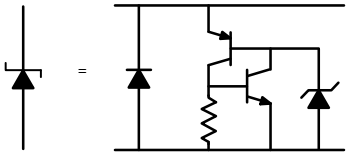
PIN CONFIGURATION AND SCHEMATIC





Pins 3, 8

Note: Common GND − Only Minimum of 1 GND connection required



ORDERING INFORMATION

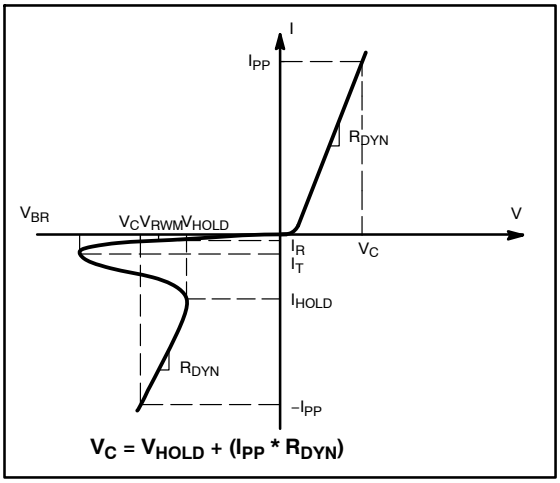
See detailed ordering, marking and shipping information in the package dimensions section on page 9 of this data sheet.

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ELECTRICAL CHARACTERISTICS

(T_A = 25°C unless otherwise noted)

Symbol	Parameter
V_{RWM}	Working Peak Voltage
I_R	Maximum Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
V_{HOLD}	Holding Reverse Voltage
I_{HOLD}	Holding Reverse Current
R_{DYN}	Dynamic Resistance
I_{PP}	Maximum Peak Pulse Current
V_C	Clamping Voltage @ I_{PP} $V_C = V_{HOLD} + (I_{PP} * R_{DYN})$



ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse Working Voltage	V_{RWM}	I/O Pin to GND			3.3	V
Breakdown Voltage	V_{BR}	I_T = 1 mA, I/O Pin to GND		5.0	6.0	V
Reverse Leakage Current	I_R	V_{RWM} = 3.3 V, I/O Pin to GND			1.0	μA
Holding Reverse Voltage	V_{HOLD}	I/O Pin to GND		1.9		V
Holding Reverse Current	I_{HOLD}	I/O Pin to GND		20		mA
Clamping Voltage	V_C	IEC61000−4−2, ±8 KV Contact				V
Clamping Voltage TLP	V_C	I_{PP} = 8 A I_{PP} = −8 A I_{PP} = 16 A I_{PP} = −16 A		4.7 −4.0 6.6 −6.7		V
Dynamic Resistance	R_{DYN}	I/O Pin to GND GND to I/O Pin		0.30 0.38		Ω
Junction Capacitance	C_J	V_R = 0 V, f = 1 MHz between I/O Pins and GND V_R = 0 V, f = 2.5 GHz between I/O Pins and GND V_R = 0 V, f = 5.0 GHz between I/O Pins and GND V_R = 0 V, f = 1 MHz, between I/O Pins		0.30 0.30 0.31 0.15	0.50 0.40 0.40 0.25	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

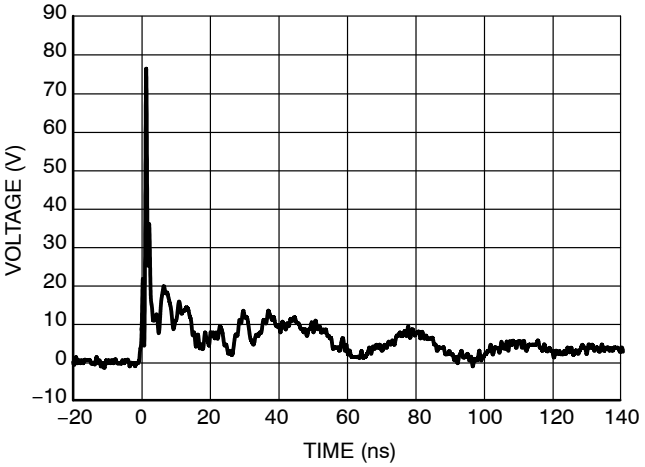


Figure 1. IEC61000−4−2 +8 kV Contact ESD Clamping Voltage

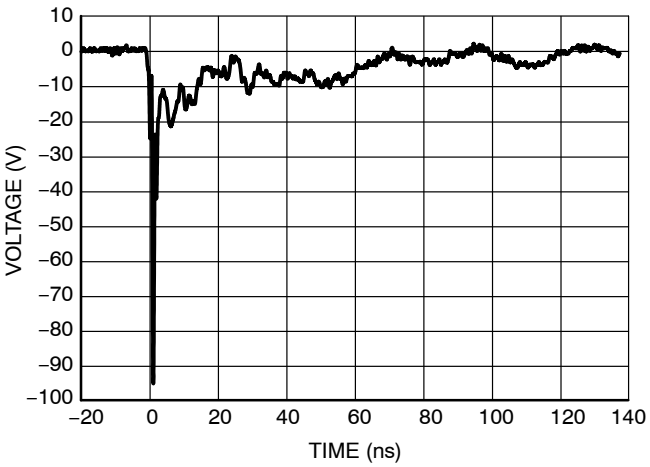


Figure 2. IEC61000−4−2 −8 kV Contact Clamping Voltage

IEC 61000−4−2 Spec.

Level	Test Voltage (kV)	First Peak Current (A)	Current at 30 ns (A)	Current at 60 ns (A)
1	2	7.5	4	2
2	4	15	8	4
3	6	22.5	12	6
4	8	30	16	8

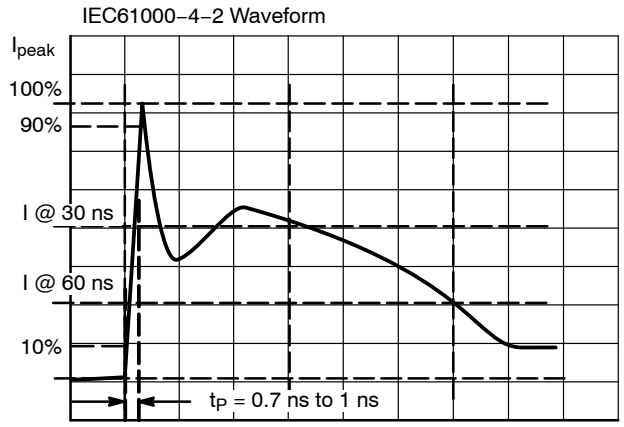


Figure 3. IEC61000−4−2 Spec

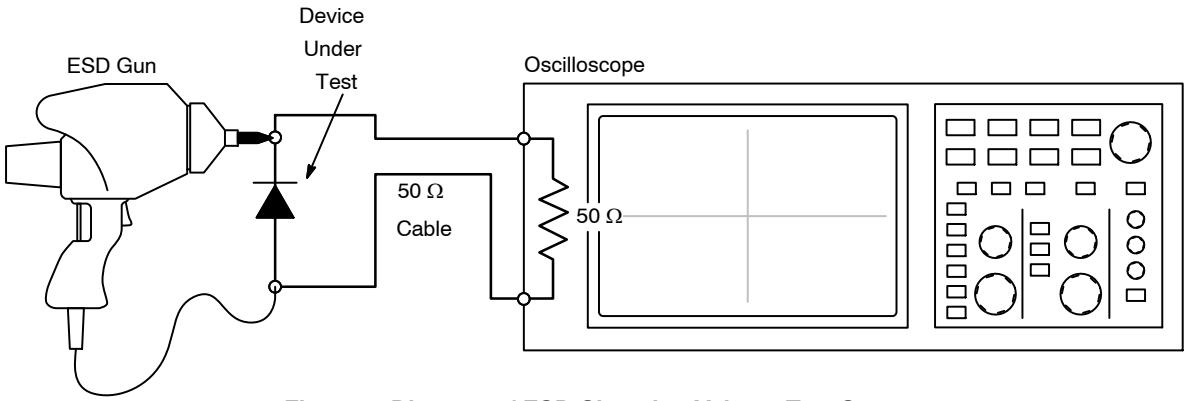


Figure 4. Diagram of ESD Clamping Voltage Test Setup

The following is taken from Application Note AND8307/D − Characterization of ESD Clamping Performance.

ESD Voltage Clamping

For sensitive circuit elements it is important to limit the voltage that an IC will be exposed to during an ESD event to as low a voltage as possible. The ESD clamping voltage is the voltage drop across the ESD protection diode during an ESD event per the IEC61000−4−2 waveform. Since the IEC61000−4−2 was written as a pass/fail spec for larger systems such as cell phones or laptop computers it is not clearly defined in the spec how to specify a clamping voltage at the device level. ON Semiconductor has developed a way to examine the entire voltage waveform across the ESD protection diode over the time domain of an ESD pulse in the form of an oscilloscope screenshot, which can be found on the datasheets for all ESD protection diodes. For more information on how ON Semiconductor creates these screenshots and how to interpret them please refer to AND8307/D.

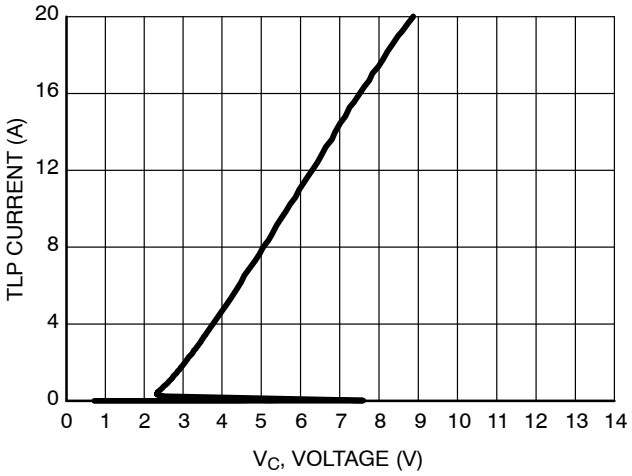


Figure 5. Positive TLP I–V Curve

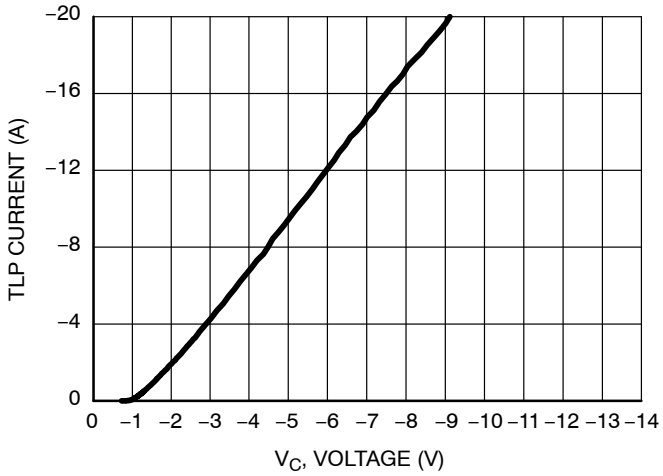


Figure 6. Negative TLP I–V Curve

NOTE: TLP parameter: Z_0 = 50 Ω, t_p = 100 ns, t_r = 300 ps, averaging window: t_1 = 30 ns to t_2 = 60 ns. V_{IEC} is the equivalent voltage stress level calculated at the secondary peak of the IEC 61000−4−2 waveform at t = 30 ns with 2 A/kV. See TLP description below for more information.

Transmission Line Pulse (TLP) Measurement

Transmission Line Pulse (TLP) provides current versus voltage (I−V) curves in which each data point is obtained from a 100 ns long rectangular pulse from a charged transmission line. A simplified schematic of a typical TLP system is shown in Figure 7. TLP I−V curves of ESD protection devices accurately demonstrate the product's ESD capability because the 10s of amps current levels and under 100 ns time scale match those of an ESD event. This is illustrated in Figure 8 where an 8 kV IEC 61000−4−2 current waveform is compared with TLP current pulses at 8 A and 16 A. A TLP I−V curve shows the voltage at which the device turns on as well as how well the device clamps voltage over a range of current levels. For more information on TLP measurements and how to interpret them please refer to AND9007/D.

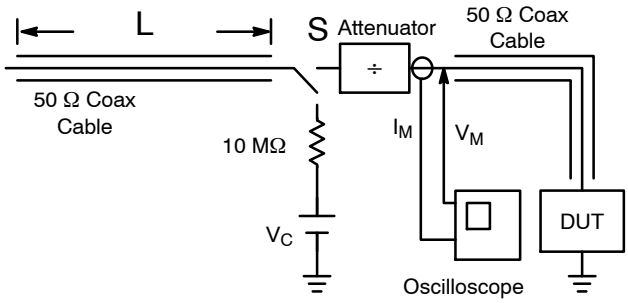


Figure 7. Simplified Schematic of a Typical TLP System

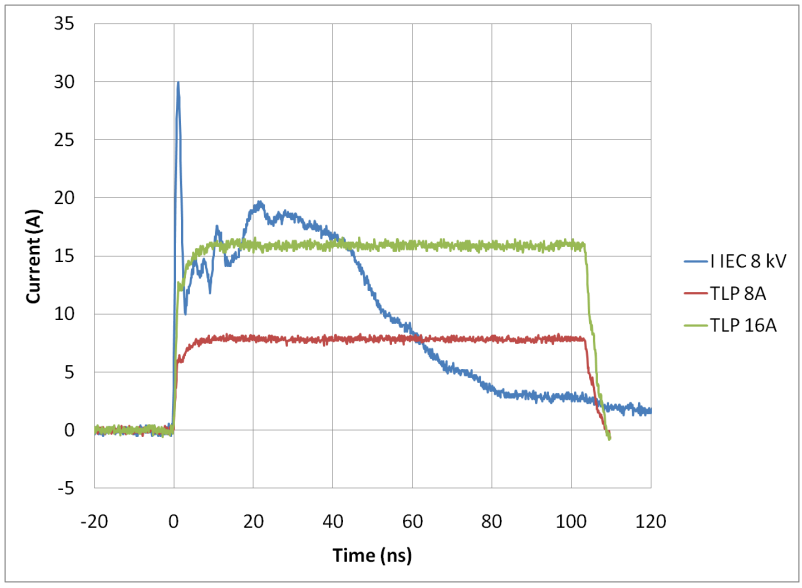


Figure 8. Comparison Between 8 kV IEC 61000−4−2 and 8 A and 16 A TLP Waveforms

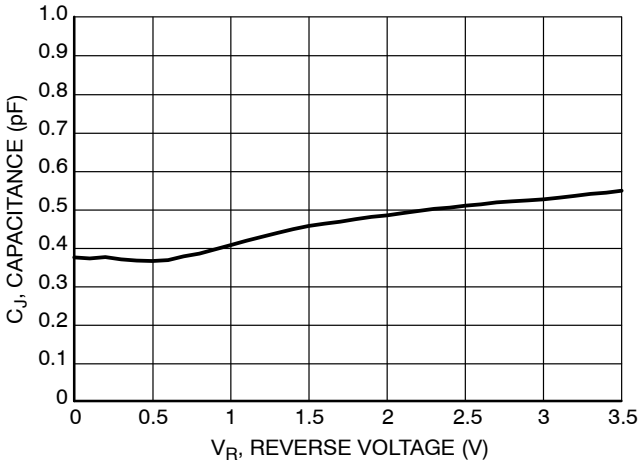


Figure 9. Junction Capacitance vs. Reverse Voltage

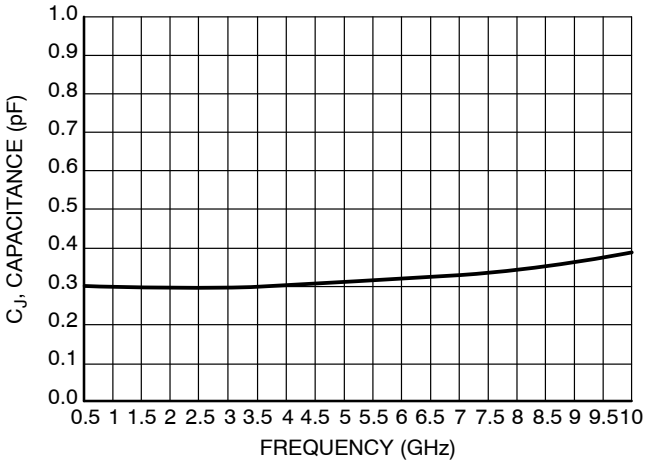
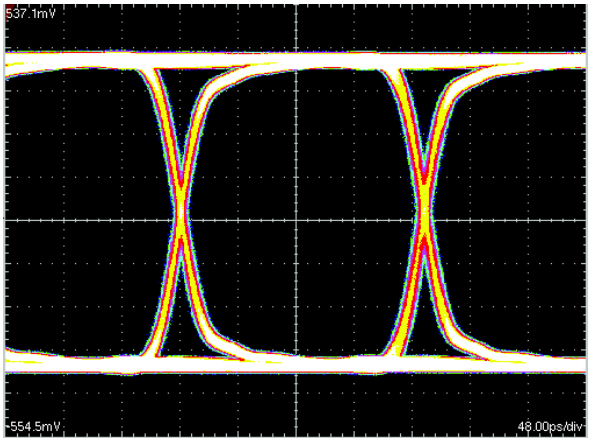
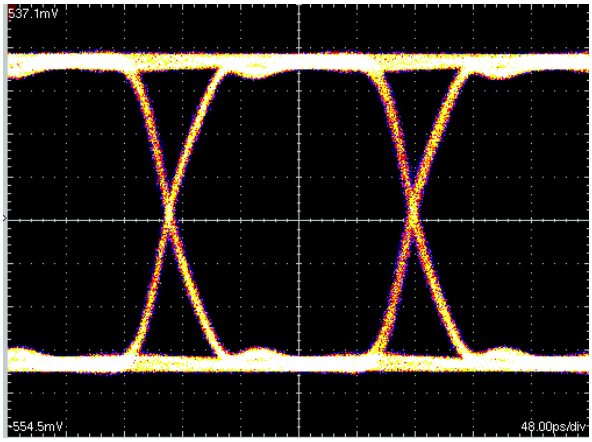


Figure 10. Junction Capacitance vs. Frequency

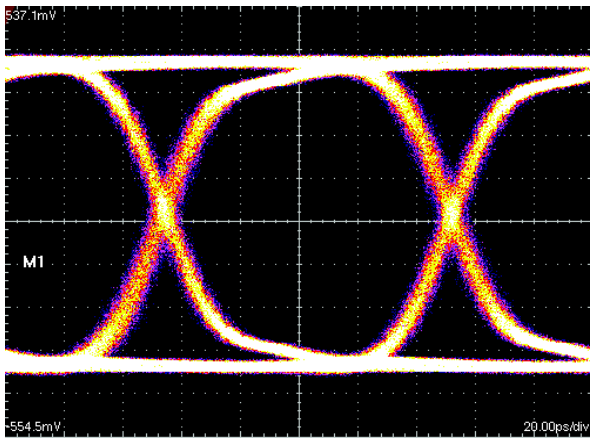


5 Gbps Eye Diagram Without ESD8704

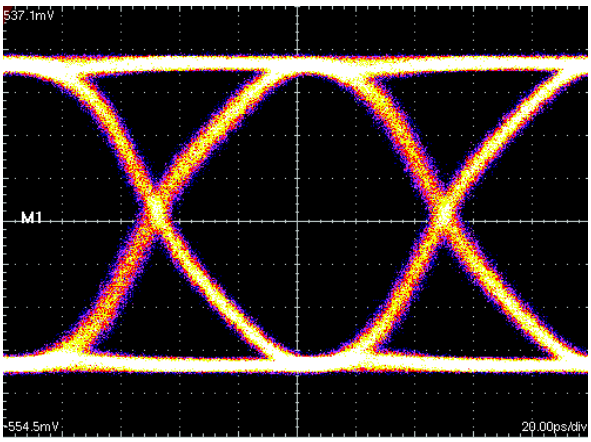


5 Gbps Eye Diagram With ESD8704

Figure 11. USB3.0 Eye Diagram with and without ESD8704. 5 Gb/s



10 Gbps Eye Diagram Without ESD8704



10 Gbps Eye Diagram With ESD8704

Figure 12. USB3.1 Eye Diagram with and without ESD8704. 10 Gb/s

See application note AND9075/D for further description of eye diagram testing methodology.

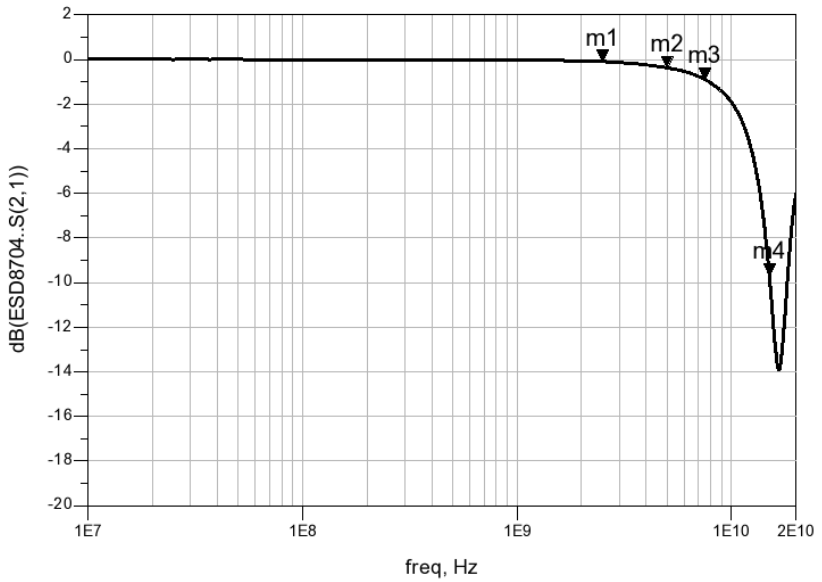


Figure 13. ESD8704 Insertion Loss

Interface	Data Rate (Gb/s)	Fundamental Frequency (GHz)	3rd Harmonic Frequency (GHz)	ESD8704 Insertion Loss (dB)
USB 3.0	5	2.5 (m1)	7.5 (m3)	m1 = −0.09 m3 = −0.89 m2 = −0.36 m4 = −9.68
USB 3.1	10	5.0 (m2)	15 (m4)	

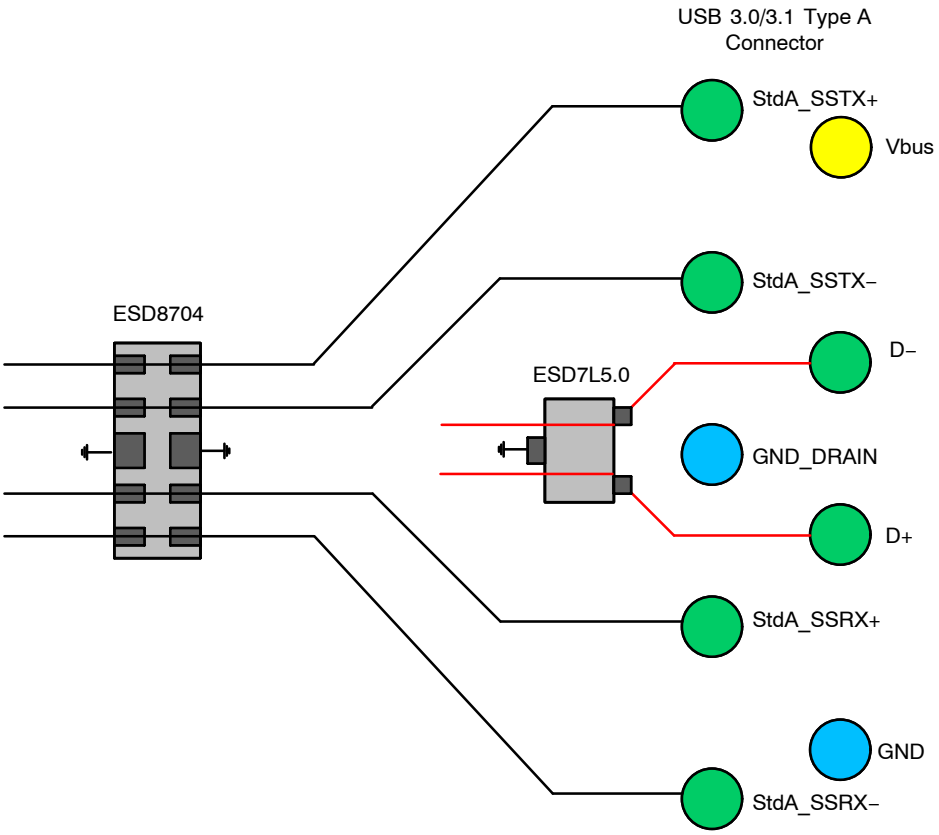


Figure 14. USB 3.0/3.1 Standard Layout Diagram

PCB Layout Guidelines

Steps must be taken for proper placement and signal trace routing of the ESD protection device in order to ensure the maximum ESD survivability and signal integrity for the application. Such steps are listed below.

- Place the ESD protection device as close as possible to the I/O connector to reduce the ESD path to ground and improve the protection performance.
  - In USB 3.0 applications, the ESD protection device should be placed between the AC coupling capacitors and the I/O connector on the TX differential lanes as shown in Figure 15. In this configuration, no DC current can flow through the ESD protection device preventing any potential latch-up condition. For more information on latchup considerations, see below description on Page 8.
- Make sure to use differential design methodology and impedance matching of all high speed signal traces.
  - Use curved traces when possible to avoid unwanted reflections.
  - Keep the trace lengths equal between the positive and negative lines of the differential data lanes to avoid common mode noise generation and impedance mismatch.
  - Place grounds between high speed pairs and keep as much distance between pairs as possible to reduce crosstalk.

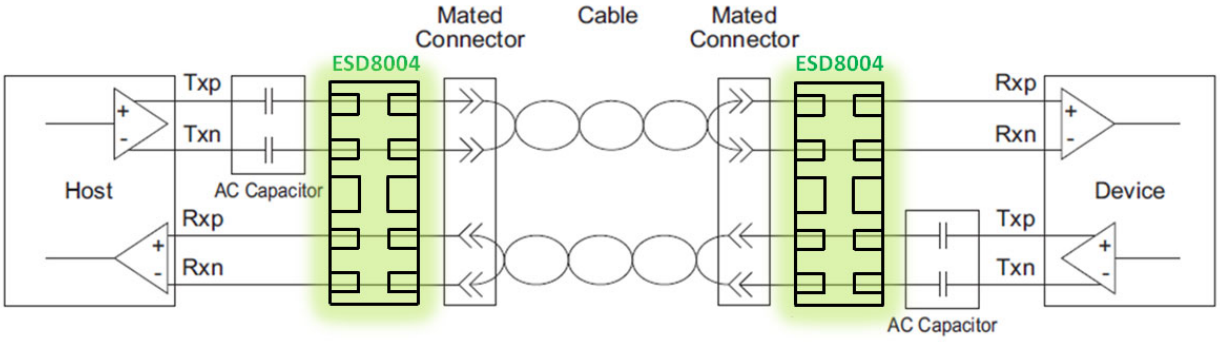
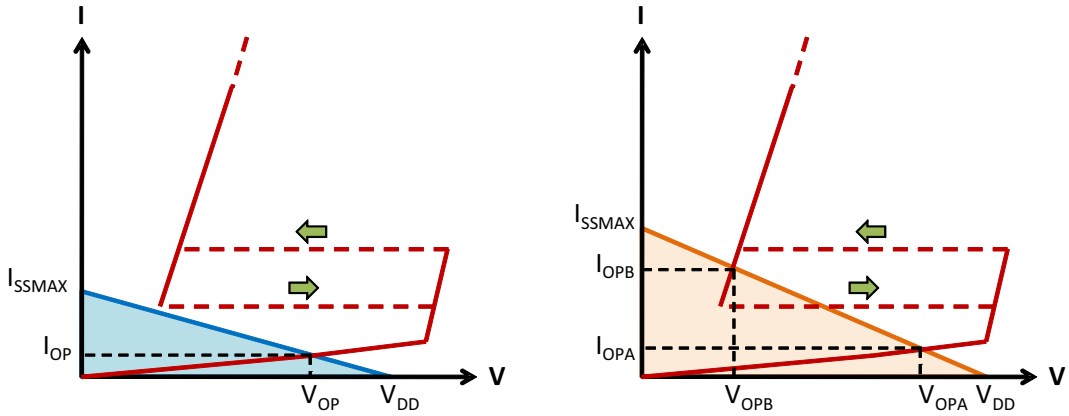


Figure 15. USB 3.0/3.1 Connection Diagram

Latch-Up Considerations

ON Semiconductor's 8000 series of ESD protection devices utilize a snap-back, SCR type structure. By using this technology, the potential for a latch-up condition was taken into account by performing load line analyses of common high speed serial interfaces. Example load lines for latch-up free applications and applications with the potential for latch-up are shown below with a generic IV characteristic of a snapback, SCR type structured device overlaid on each. In the latch-up free load line case, the IV characteristic of the snapback protection device intersects the load-line in one unique point (V_{OP}, I_{OP}). This is the only stable operating point of the circuit and the system is therefore latch-up free. Please note that for USB 3.0 applications, ESD8704 latch-up free considerations are explained in more detail in the above PCB layout guidelines. In the non-latch up free load line case, the IV characteristic of the snapback protection device intersects the load-line in two points (V_{OPA}, I_{OPA}) and (V_{OPB}, I_{OPB}). Therefore in this case, the potential for latch-up exists if the system settles at (V_{OPB}, I_{OPB}) after a transient. Because of this, ESD8704 should not be used for HDMI applications – ESD8104 or ESD8040 have been designed to be acceptable for HDMI applications without latch-up. Please refer to Application Note AND9116/D for a more in-depth explanation of latch-up considerations using ESD8000 series devices.



ESD8704 Latch−up free:
USB 2.0 LS/FS, USB 2.0 HS, USB 3.0/3.1 SS, DisplayPort

ESD8704 Potential Latch−up:
HDMI 1.4/1.3a TMDS

Figure 16. Example Load Lines for Latch-up Free Applications and Applications with the Potential for Latch-up

Table 1. SUMMARY OF SCR REQUIREMENTS FOR LATCH-UP FREE APPLICATIONS

Application	VBR (min) (V)	IH (min) (mA)	VH (min) (V)	ON Semiconductor ESD8000 Series Recommended PN
HDMI 1.4/1.3a TMDS	3.465	54.78	1.0	ESD8104, ESD8040
USB 2.0 LS/FS	3.301	1.76	1.0	ESD8704
USB 2.0 HS	0.482	N/A	1.0	ESD8704
USB 3.0/3.1 SS	2.800	N/A	1.0	ESD8704, ESD8006
DisplayPort	3.600	25.00	1.0	ESD8704, ESD8006

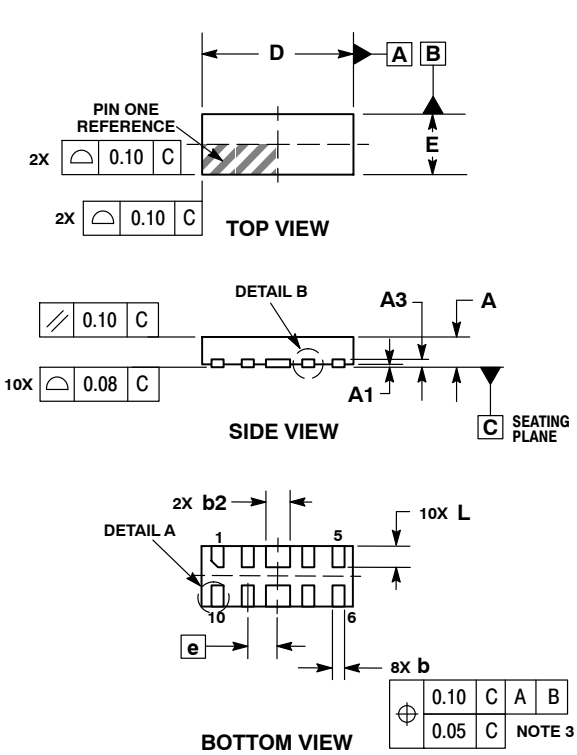
DEVICE ORDERING INFORMATION

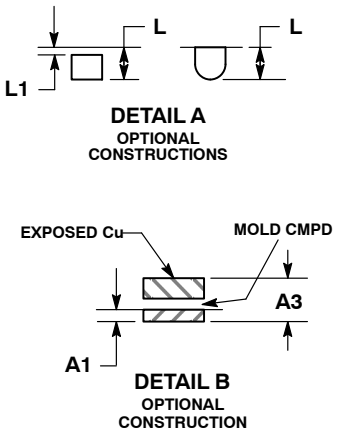
Device	Marking	Package	Shipping†
ESD8704MUTAG	7D	UDFN10 (Pb−Free)	3000 / Tape & Reel
SZESD8704MUTAG	7D	UDFN10 (Pb−Free)	3000 / Tape & Reel
SZESD8704MTWTAG (In Development)	AAA	WDFNW10 (Pb−Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS

UDFN10 2.5 x 1, 0.5P
CASE 517BB
ISSUE O

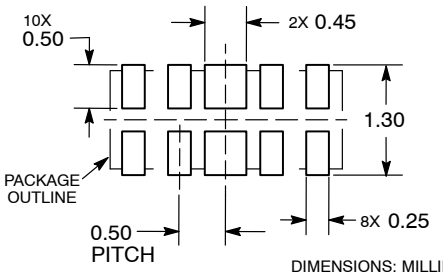




NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30mm FROM TERMINAL.

	MILLIMETERS	
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13 REF	
b	0.15	0.25
b2	0.35	0.45
D	2.50 BSC	
E	1.00 BSC	
e	0.50 BSC	
L	0.30	0.40
L1	---	0.05

RECOMMENDED SOLDERING FOOTPRINT*



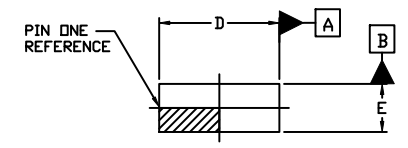
DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

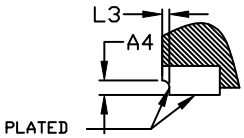
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PACKAGE DIMENSIONS

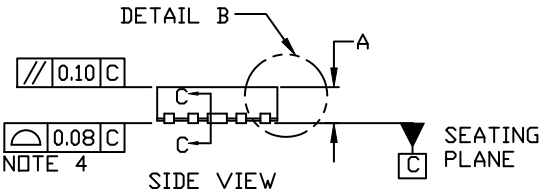
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CASE 515AH
ISSUE A



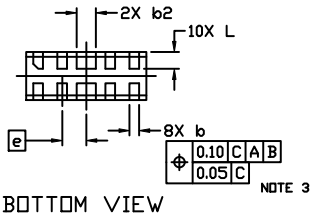
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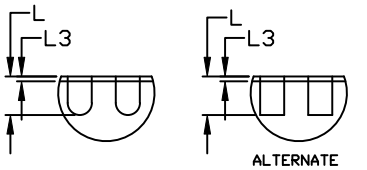
SECTION C-C
8X



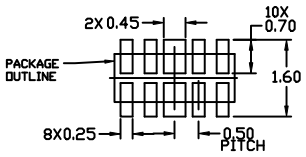
SIDE VIEW



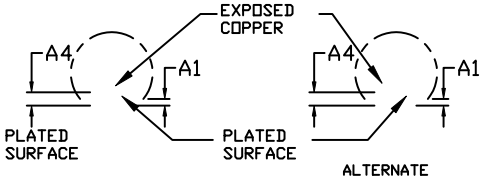
BOTTOM VIEW



DETAIL A



RECOMMENDED MOUNTING FOOTPRINT



DETAIL B

* For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO PLATED TERMINALS AND IS MEASURED BETWEEN 0.15 AND 0.30MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. THIS DEVICE CONTAINS WETTABLE FLANK DESIGN FEATURES TO AID IN FILLET FORMATION ON THE LEADS DURING MOUNTING.

	MILLIMETERS		
DIM	MIN.	NOM.	MAX.
A	0.70	0.75	0.80
A1	0.00	---	0.05
A3	0.13 REF		
A4	0.10	---	---
b	0.15	0.20	0.25
b2	0.35	0.40	0.45
D	2.40	2.50	2.60
E	0.90	1.00	1.10
e	0.50 BSC		
L	0.30	0.35	0.40
L3	---	---	0.10

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